

APPLICATION INFORMATION
**ADDITIVES FOR INSULATING MATERIALS FOR USE IN THE
ELECTRICAL AND ELECTRONICS INDUSTRY**



Contents

- 03** Insulating materials for the electrical and electronics industry
- 04** Electrical insulating systems
- 05** Air release additives
- 07** Wetting and dispersing additives
- 08** Rheology additives
- 11** Surface-active additives

Insulating materials for the electrical and electronics industry

Insulating materials based on organic resin systems are used in electric motors, cars, television sets, computers, and many other devices. As a result of the large number of different applications, the requirements on the insulating systems also differ considerably.

In addition to a series of electrical characteristic values such as resistance, dielectric strength, and dielectric dissipation factor, other physical properties such as thermal conductivity, combustibility, and chemical resistance may also be of key importance.

Not least, factors such as processability, quality, and price also influence the selection of the correct system. By using suitable additives, it is possible to markedly improve all of these properties and the quality of the insulating materials.

This brochure summarizes our additive recommendation for this application.

For additional information on additives and technical topics, please contact us:
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Note

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Electrical insulating systems

Electrical insulating systems can be subdivided into three main groups (G.01):

Primary insulation: Primary insulation is the first insulating layer that is applied directly on the electrical conductor. Primary insulating materials are wire enamels.

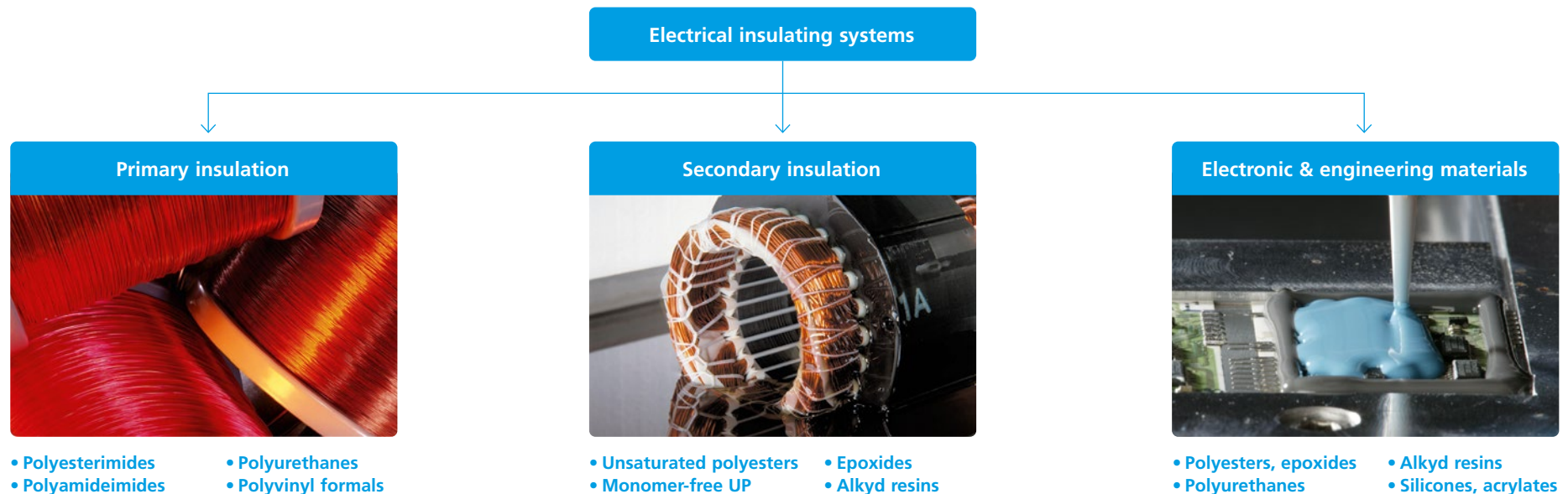
Secondary insulation: Secondary insulation, also called impregnation, describes the next stage of insulation. It

improves the entire electrical insulation and protects it against external influences. It is used in motors, generators, and stationary electrical machines such as transformers and sensors.

Electronic & engineering materials (E & E): These systems refer to insulating and construction materials that are used to embed, completely encapsulate, or coat electrical and electronic components.

The following recommendations predominantly apply to secondary insulation and E&E, although they may also be used in the field of primary insulation.

Classification of electrical insulating systems and frequently used resin systems



Air release additives

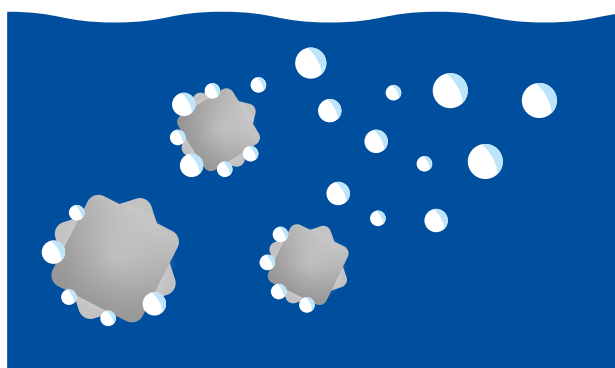
In electrical insulation systems, the electrical and mechanical properties of the respective resin system are of particular importance. So that these properties are utilized to the greatest possible effect, it is important to prevent air bubbles remaining in the system after curing. Air inclusions have an adverse effect on the electrical and mechanical properties and, at worst, may lead to a premature breakdown of the component.

Air can get into the insulating material via fillers and pigments, or air can be trapped as a result of dispersion and agitation processes during manufacture or when using the material.

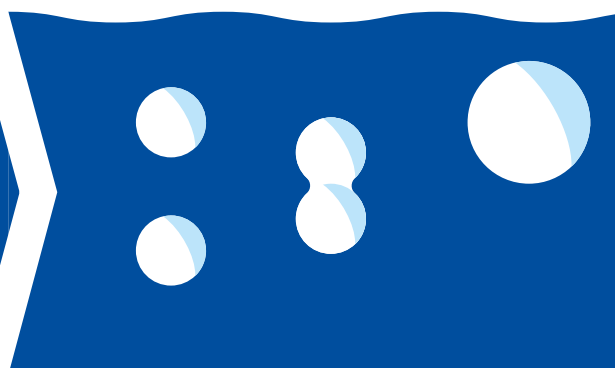
Air release agents work in three steps (G.02): Firstly, the air attached to the surface of the pigments/fillers is detached from the solid particles; small air bubbles coalesce to form larger bubbles, which can then rise faster to the surface due to their greater buoyancy. Finally, the bubbles burst at the surface.

Air release agents work in three steps

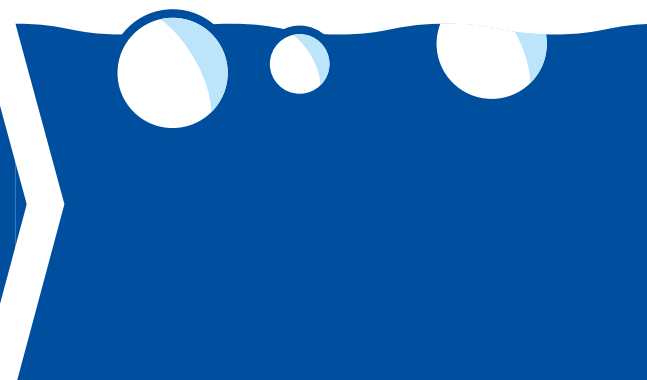
Step 1



Step 2



Step 3



To achieve optimum air release, resin-specific additives are used that enable spontaneous air release and significantly accelerate degassing under vacuum. In all cases, the aim is to drastically reduce the air inclusions in cured systems (G.03).

Air release agent recommendations

System	General applications	VOC-free systems	Transparent systems
Epoxy	BYK-A 501* BYK-A 530	BYK-1794* BYK-P 9920	BYK-141* BYK-A 500*
Polyurethane	BYK-088	BYK-1790* BYK-A 535*	BYK-141*
Unsaturated polyester (also monomer-free)	BYK-A 515* BYK-A 555*		BYK-A 500*

* silicone-free

T.01

Significant reduction of air entrapments by using 0.3 % BYK-A 555 in an unsaturated polyester resin



Wetting and dispersing additives

Wetting and dispersing additives are needed if the insulating system contains pigments and/or fillers. Pigments are used to color the system; fillers are used to reduce costs, but are also able to improve certain physical properties, such as thermal conductivity or flame retardancy.

When incorporating fillers or pigments in the resin system, the viscosity of the formulation increases. The flow behavior that is modified in this way can make the system more difficult to process. Viscosity can be significantly reduced through the use of suitable additives that improve the wetting of solid particles and prevent flocculation of the particles (G. 05), or by increasing the filler content at the same viscosity.

In some systems, the fillers and pigments settle during storage and sediment forms. This also makes the system difficult to process. In these cases, suitable wetting and dispersing additives are also able to stabilize the dispersion of the solid particles against sedimentation (G. 04).

Stabilization of a filler dispersion against settling



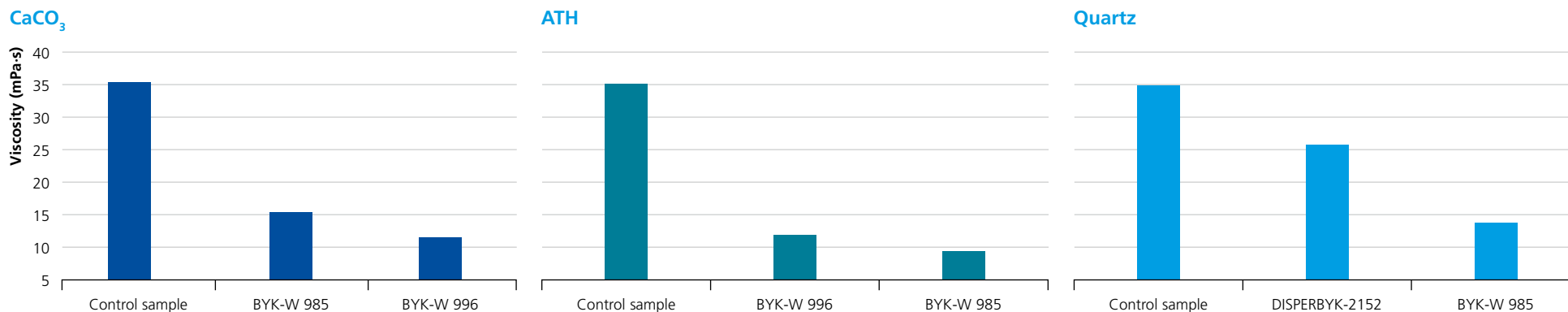
G.04

Wetting and dispersing additives

System	Viscosity reduction	Anti-settling
Epoxy	BYK-W 980 BYK-W 985 BYK-W 996 DISPERBYK-2152	ANTI-TERRA-204 BYK-W 940
Polyurethane	BYK-9076 BYK-W 903 BYK-W 969 BYK-W 996	BYK-W 961
Unsaturated polyester (also monomer-free)	BYK-W 908 BYK-W 966 BYK-W 985 DISPERBYK-2152	BYK-W 940

T.02

Viscosity reduction of a filled electrical insulating system using wetting and dispersing additives



Rheology additives

Flow behavior is one of the most important properties of an electrical insulating system with regard to material processing. For easy processing, the material needs to be fluid, though it must be ensured that the layer thickness does not fall short of that required for the insulating effect.

The viscosity, its dependence on the arising shear forces, and also its time dependence (thixotropy) play a major role here.

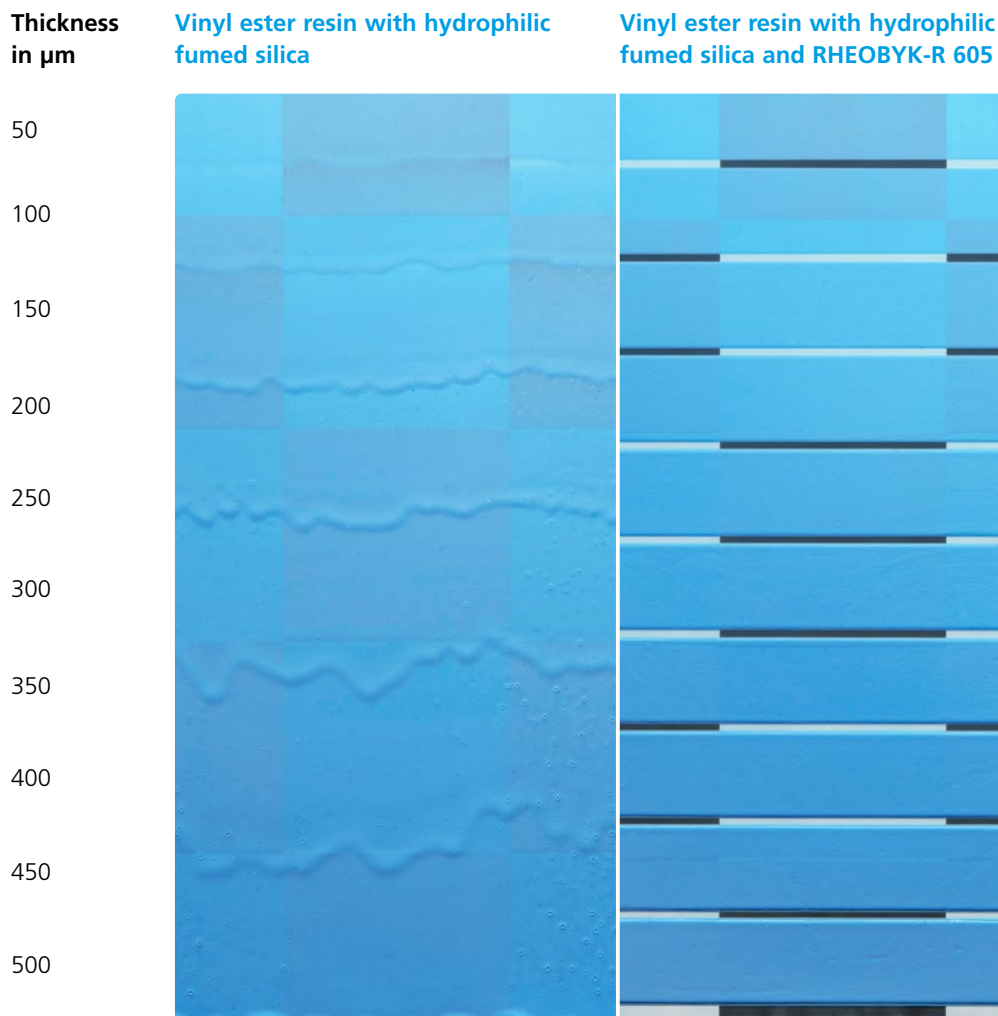
Rheology additives are able to adjust the flow behavior in such a way that the insulating materials can be easily processed and simultaneously exhibit a high stability (no sagging).

This also enables the settling behavior to be controlled, so that there is no sedimentation of the solids (fillers, pigments) in the resin during storage.

RHEOBYK-410 is a liquid rheology additive used to generate and enhance thixotropy. It is stirred into the system as a liquid and forms a three-dimensional network structure to create highly thixotropic behavior. It acts as an anti-settling additive and increases the sag resistance of the system.

RHEOBYK-R 605, the thixotropy booster. Often, GARAMITE or hydrophilic fumed silica is used to control rheology, which also create thixotropy by forming network structures. RHEOBYK-R 605 enhances thixotropy in such systems by producing an even closer-meshed network via the hydroxyl groups of the silica (G.06). The additive does not work with hydrophobic fumed silica.

Major sagging in a material with fumed silica (left) and excellent stability (right) if RHEOBYK-R 605 is used in addition



RHEOBYK-R 607 works in a similar way and is specifically recommended for epoxy resins. If GARAMITE or hydrophilic fumed silica is used in an epoxy resin, there is hardly any thixotropy due to the high polarity of the resin; the resin therefore remains highly fluid. If this resin is mixed with a hardener that contains RHEOBYK-R 607, the additive activates the solid thixotrope in the overall mixture and a highly thixotropic system with considerably high sag resistance is produced. RHEOBYK-R 607 makes a very viscous mixture out of two low viscous components (G.07).

A particularly high thixotropy is achieved in epoxy systems using a combination of RHEOBYK-R 607 and GARAMITE-7305.

Rheology additives

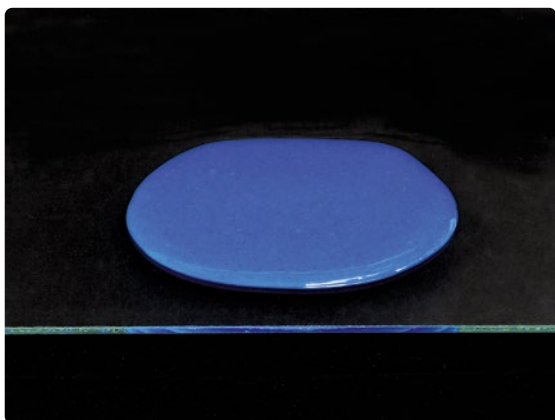
System	Thixotropy booster	Liquid thixotropic additive	Solid thixotrope	Viscosity control technology
Epoxy	RHEOBYK-R 605 RHEOBYK-R 607*	RHEOBYK-410	GARAMITE-7305	BYK-P 2710 BYK-P 2720
Polyurethane	RHEOBYK-R 605	RHEOBYK-410		
Unsaturated polyester (also monomer-free)	RHEOBYK-R 605		GARAMITE-1958	

* for the hardener

T.03

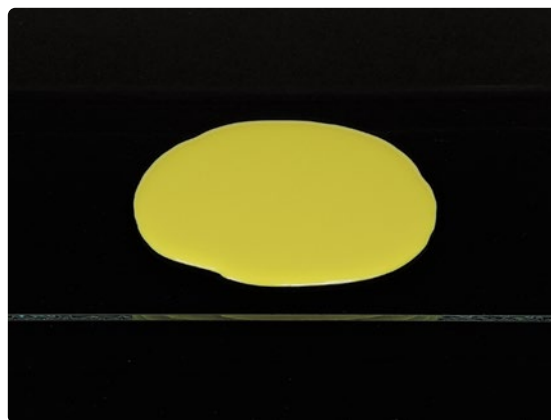
Thixotropy enhancement in a fumed silica-based epoxy resin using RHEOBYK-R 607

Epoxy resin with hydrophilic fumed silica



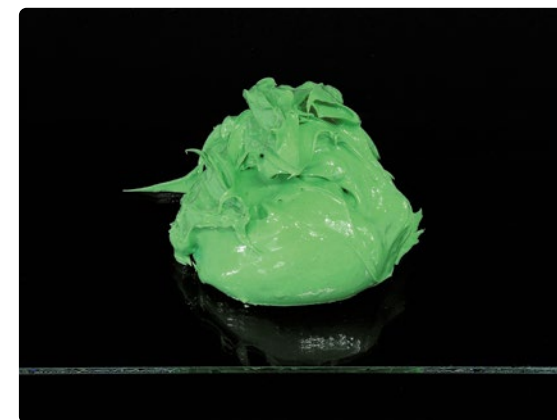
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Amine hardener with RHEOBYK-R 607



=

Thixotropic mixture



Viscosity control technology (VCT) – processing additives for epoxy systems

BYK-P 2710 and BYK-P 2720 are recommended for solvent-free and solvent-borne epoxy resins containing hydrophilic fumed silica for anti-sagging properties in medium/high-viscosity systems.

BYK-P 2710 – Thixbreaker

- Add to epoxy resin
- Effective with hydrophilic fumed silica
- Resin viscosity can be adjusted and controlled
- A high amount of additive blocks the structural build-up of the hydrophilic fumed silica and avoids an increase in viscosity

BYK-P 2720 – Thixbooster

- Add to amine hardener
- Effective with hydrophilic fumed silica
- Hardener viscosity can be adjusted and controlled
- Dosage must always be calculated based on the amount of hydrophilic fumed silica in the entire system

Better mixing and improved application viscosities due to our viscosity control technology (VCT)

BYK-P 2710 – Thixbreaker



BYK-P 2720 – Thixbooster



VCT adjusted viscosities lead to better and easier mixing...



...and instantly maintain a high application viscosity



Surface-active additives

Surface-active additives are used to prevent surface defects or improve the resin's penetration in a component. Typical surface defects are, for example, poor substrate wetting and cratering. A fundamental parameter in all effects of this kind is the surface tension of the materials involved. If the surface tension of the coating is reduced, this improves the substrate wetting and prevents craters forming. Modified polysiloxanes ("silicones") are widely used to reduce surface tension.

These products also improve the penetration of the resin in a component, as the adhesion to the component is stronger than the cohesion of the liquid particles to each other. This makes it easier for the resin to penetrate the component.

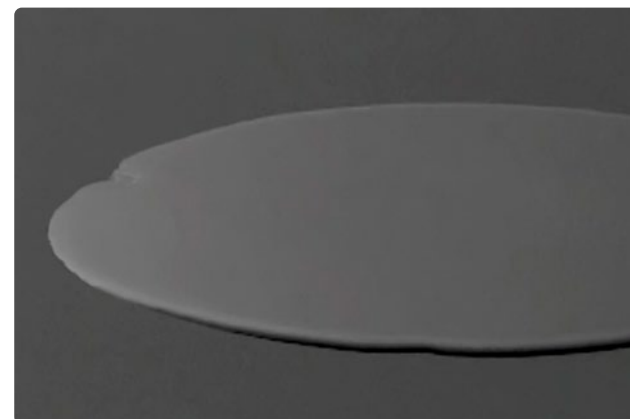
Besides modified polysiloxanes, surface-active additives that are based on polyacrylates are also used. These products can also prevent cratering and leveling defects, however, they do not reduce surface tension or do so only to a very minor extent.

Improved substrate wetting using a silicone-based additive that reduces surface tension

Poor substrate wetting



Reduction of the surface tension using a silicone-based additive: better substrate wetting



G.09

Surface-active additives

System	Silicone-based	Acrylate-based (silicone-free)
Epoxy	BYK-307 BYK-310 BYK-320	BYK-358 N BYK-S 706
Polyurethane	BYK-307	BYK-S 706
Unsaturated polyester (also monomer-free)	BYK-306 BYK-330 BYK-370	BYK-361 N

T.04

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This issue replaces all previous versions.

